

AMENDMENTS TO THE CLAIMS:

Please amend the claims as follows.

Claims 1 - 8 (Withdrawn)

Claim 9. (Currently Amended) An apparatus comprising a substrate assembly including a semiconductor substrate having a top and bottom surface, wherein an optoelectronic light-emitting device is disposed on a the top surface thereof and a ;and

a ceramic mounting substrate coupled to said semiconductor substrate, said ceramic mounting substrate having a top and bottom surface, wherein a photodetector device is disposed below on a bottom on the top surface thereof and is capable of detecting light emitted by said optoelectronic device,

wherein said semiconductor substrate includes a transparent, overhanging pass through portion and a portion of said light-emitting optoelectronic device is disposed on said overhanging portion and said photodetector is disposed below said overhanging portion which permits light emitted by said optoelectronic device to pass through said overhanging portion and be received by said photodetector.

Claim 10. (Original) The apparatus as in claim 9, further comprising a semiconductor substrate interposed between said semiconductor substrate and said photodetector, said further semiconductor substrate being transparent to said light emitted by said optoelectronic device.

Claim 11. (Currently Amended) The apparatus as in claim 10, in which said optoelectronic device comprises a vertical cavity surface emitting laser ~~and said photodetector is formed on said substrate assembly beneath an overhang portion of said semiconductor substrate and said further semiconductor substrate.~~

Claim 12. (Original) The apparatus as in claim 9, in which said light emitted by said optoelectronic device includes a wavelength being at least 1.25 microns.

Claim 13. (Original) The apparatus as in claim 9, wherein said pass through portion comprises at least one of a transparent material or notch.

Claim 14. (Original) An optical subassembly module comprising a base unit having a pair of guide pins passing through a substrate assembly and a ferrule, said substrate assembly ~~includes~~ including a U-shaped weld plate with a notch therein, said plate having a VCSEL array and a photodiode disposed thereon, and a ceramic substrate having a photodetector device disposed thereon, wherein said plate and ceramic substrate are bonded together and said photodiode is capable of detecting a light wavelength emitted by said VCSEL array that passes through the notch, and wherein ~~said conventional~~ an optical ferrule is spaced apart from said VCSEL array by a medium that is transparent to said light wavelength.

Claim 15. (Original) The optical subassembly module of claim 14, wherein said medium is at least one of an epoxy layer, a flip chip lens, and a lens array.

Claim 16. (Original) The optical subassembly module of claim 14, further comprising a connector latch in mechanical communication with said base unit.

Claim 17. (Canceled)

Claim 18. (Currently Amended) The optical subassembly module of claim 14, further comprising a lens frame and an adjustable stop member, said adjustable stop member is configured to adjust a gap between ~~said conventional~~ the optical ferrule and a lens array.

Claim 19. (Original) The optical subassembly module of claim 14, further comprising a VCSEL frame and wherein said VCSEL frame includes a recess for receiving said VCSEL array.

Claim 20. (Canceled)

AMENDMENTS TO THE SPECIFICATION:

Please amend the specification at page 2, lines 28-31 as follows.

In an exemplary embodiment, the present invention provides a VCSEL array within an optical subassembly module with an ~~alignment~~-a alignment connectorized array of VCSELs with high coupling efficiency ~~includes~~ including a photodetector capable of monitoring the representative optical output of the VCSELs.

/

//

///